

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

CORRECTED VERSION

10/538275

(19) World Intellectual Property Organization  
International Bureau



(43) International Publication Date  
24 June 2004 (24.06.2004)

PCT

(10) International Publication Number  
WO 2004/053973 A1

(51) International Patent Classification<sup>7</sup>: H01L 21/56,  
23/28, 23/31, 23/495

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(21) International Application Number:

PCT/SG2002/000288

(81) Designated States (national): DE, SG, US.

(22) International Filing Date:

10 December 2002 (10.12.2002)

Declaration under Rule 4.17:

— of inventorship (Rule 4.17(iv)) for US only

(25) Filing Language:

English

Published:

— with international search report

(26) Publication Language:

English

(48) Date of publication of this corrected version:

10 September 2004

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(15) Information about Correction:

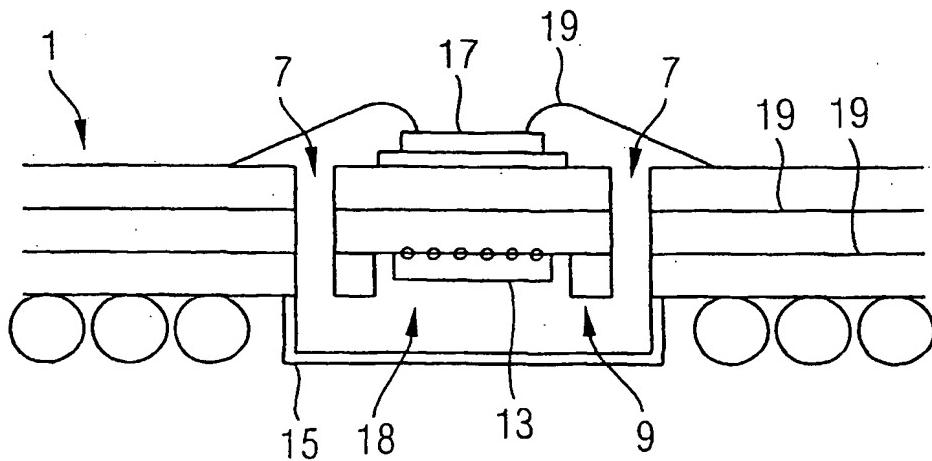
see PCT Gazette No. 37/2004 of 10 September 2004, Section II

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For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF PACKAGING INTEGRATED CIRCUITS, AND INTEGRATED CIRCUIT PACKAGES PRODUCED BY THE METHOD



(57) Abstract: A method of packaging integrated circuits is proposed in which two integrated circuits 13, 17 are provided in register on opposite sides of a single substrate 1. Electrical contacts on each of the integrated circuits 13, 17 are electrically connected to electrical conductors of the substrate 1. One of the integrated circuits 17 may be wire bonded to the substrate, while the other is a flip-chip 13. Holes 7 are provided through the substrate 1 so that in a moulding operation a single resin body 21 may be formed encasing both of the integrated circuits 13, 17 by applying resin only to an upper side of the substrate 1 and allowing the resin to flow to the other side of the substrate 1 into a volume defined by a box 15.

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